

Global Silver Sintering Die Bonding Equipment Supply, Demand and Key Producers, 2026-2032

<https://marketpublishers.com/r/GA75161CD367EN.html>

Date: July 2026

Pages: 147

Price: US\$ 4,480.00 (Single User License)

ID: GA75161CD367EN

Abstracts

The global Silver Sintering Die Bonding Equipment market size is expected to reach \$ 222 million by 2032, rising at a market growth of 6.8% CAGR during the forecast period (2026-2032).

Silver sintering die bonding equipment refers to dedicated die placement and sintering bonding systems used in power semiconductor and high-reliability electronic packaging. By using silver sintering paste, silver sintering film or silver preforms under controlled temperature, pressure, time, atmosphere and placement accuracy, the equipment forms low-void, high-thermal-conductivity, high-electrical-conductivity and thermally robust solid-state interconnects between bare dies, power chips, clips, DTS structures, DBC/AMB substrates, leadframes or power module carriers. A typical system consists of die feeding, vision alignment, silver material transfer or placement, thermo-compression bonding, sintering chamber, closed-loop pressure control, temperature control, atmosphere protection, tooling, automated loading/unloading and process traceability modules. By configuration, it includes semi-automatic die bonding equipment, fully automatic die bonding equipment, offline silver sintering systems and inline silver sintering production systems. Major production bases are concentrated in China, Singapore, Germany, Italy, the Netherlands, Switzerland, Japan and the United States, with applications in SiC power modules, IGBT modules, automotive inverters, industrial drives, power supply modules, RF power devices and aerospace-grade high-reliability electronic packaging.

In 2025, global silver sintering die bonding equipment production reached approximately 170-205 units, with mainstream factory-gate FOB prices of about USD 650,000-850,000 per unit. Fully automatic inline tools, large-area multi-press-head systems for automotive-grade SiC power modules, and high-end models equipped with vacuum

assistance, atmosphere protection, process traceability and high-precision closed-loop pressure control were generally positioned at the upper end of the price range, while R&D, semi-automatic and offline systems were priced lower.

Global silver sintering die bonding equipment is becoming a key equipment category in the upgrade of power semiconductor packaging. Electric vehicle high-voltage platforms, 800V e-drive systems, SiC power modules, industrial inverters, photovoltaic inverters, energy storage PCS and high-reliability power systems are raising requirements for thermal conductivity, high-temperature endurance, thermal-cycle lifetime and long-term interconnect stability. These trends are driving silver sintering from a high-end qualification process toward scaled mass production. Compared with conventional soft soldering and certain conductive adhesive interconnects, silver sintering bonding offers advantages in high-temperature operation, low thermal resistance, low voiding and higher power density, expanding equipment demand from standalone sintering presses to integrated production-line solutions covering silver material placement, die bonding, pressure sintering, inline inspection and data traceability.

However, commercialization is still constrained by process complexity and long customer qualification cycles. Silver material format, die metallization, substrate surface condition, sintering pressure, temperature uniformity, atmosphere control and tooling design directly affect bond strength, void ratio and reliability, so end customers typically require extended process development, sample validation and automotive-grade qualification. Future competition will focus on large-area uniform pressure, independent multi-die pressing, high-accuracy placement, low-damage pressure control, vacuum or inert-atmosphere sintering, equipment stability, automation throughput and MES data connectivity. As SiC module capacity expands and power packaging localization accelerates, equipment supply chains in China, Europe, Japan and Singapore are expected to benefit from the long-term transition of power semiconductor packaging toward higher reliability, higher power density and intelligent manufacturing.

This report studies the global Silver Sintering Die Bonding Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Silver Sintering Die Bonding Equipment and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Silver Sintering Die Bonding Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Silver Sintering Die Bonding Equipment total production and demand, 2021-2032, (Units)

Global Silver Sintering Die Bonding Equipment total production value, 2021-2032, (USD Million)

Global Silver Sintering Die Bonding Equipment production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Units), (based on production site)

Global Silver Sintering Die Bonding Equipment consumption by region & country, CAGR, 2021-2032 & (Units)

U.S. VS China: Silver Sintering Die Bonding Equipment domestic production, consumption, key domestic manufacturers and share

Global Silver Sintering Die Bonding Equipment production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Units)

Global Silver Sintering Die Bonding Equipment production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Units)

Global Silver Sintering Die Bonding Equipment production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Units)

This report profiles key players in the global Silver Sintering Die Bonding Equipment market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include ASMPT Limited, Suzhou Bopai Semiconductor Technology Co., Ltd. (Boschman), AMX Automatrix S.r.l., PINK GmbH Thermosysteme, Nikkiso Co., Ltd., Palomar Technologies, Inc., BE Semiconductor Industries N.V., Infotech AG, Tresky GmbH, Mycronic AB (MRSI Systems), etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Silver Sintering Die Bonding Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Units) and average price (US\$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Silver Sintering Die Bonding Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Silver Sintering Die Bonding Equipment Market, Segmentation by Type:

Offline Sintering Equipment

Inline Sintering Equipment

Die Bonder With Sintering Function

Others

Global Silver Sintering Die Bonding Equipment Market, Segmentation by Process Pressure:

Pressure Silver Sintering Equipment

Low-Pressure Silver Sintering Equipment

Pressureless Silver Sintering Equipment

Others

Global Silver Sintering Die Bonding Equipment Market, Segmentation by Automation Level:

Fully Automatic Equipment

Semi-Automatic Equipment

Manual and Laboratory Equipment

Global Silver Sintering Die Bonding Equipment Market, Segmentation by End-Use Industry:

Electric Vehicle and Automotive Electronics

Industrial Power Electronics

Renewable Energy and Energy Storage

Others

Global Silver Sintering Die Bonding Equipment Market, Segmentation by Application:

SiC Power Module Packaging

IGBT Power Module Packaging

Discrete Power Device Packaging

Others

Companies Profiled:

ASMPT Limited

Suzhou Bopai Semiconductor Technology Co., Ltd. (Boschman)

AMX Automatrix S.r.l.

PINK GmbH Thermosysteme

Nikkiso Co., Ltd.

Palomar Technologies, Inc.

BE Semiconductor Industries N.V.

Infotech AG

Tresky GmbH

Mycronic AB (MRSI Systems)

Zhuhai Silicon Cool Technology Co., Ltd.

Shenzhen Advanced Joining Technologies Co., Ltd.

Quick Intelligent Equipment Co., Ltd.

Chenglian Kaida (Hebei) Technology Co., Ltd.

JH Advanced Semiconductor (Suzhou) Co., Ltd.

Zhongke Guangzhi (Chongqing) Technology Co., Ltd.

Torch Semiconductor Co., Ltd.

CYG Semiconductor Equipment (Zhuhai) Co., Ltd.

Key Questions Answered:

1. How big is the global Silver Sintering Die Bonding Equipment market?

2. What is the demand of the global Silver Sintering Die Bonding Equipment market?
3. What is the year over year growth of the global Silver Sintering Die Bonding Equipment market?
4. What is the production and production value of the global Silver Sintering Die Bonding Equipment market?
5. Who are the key producers in the global Silver Sintering Die Bonding Equipment market?
6. What are the growth factors driving the market demand?

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